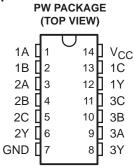
- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- 2-V to 5.5-V V_{CC} Operation

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC}= 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation



description/ordering information

This triple 3-input positive-AND gate is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV11A performs the Boolean function $Y = A \bullet B \bullet C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACK	\GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP - PW	Tape and reel	SN74LV11ATPWREP	LV11AEP

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

	INPUTS	OUTPUT	
Α	В	С	Y
Н	Н	Н	Н
L	X	Χ	L
Х	L	Χ	L
Х	Χ	L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN74LV11A-EP TRIPLE 3-INPUT POSITIVE-AND GATE

SCLS564A - JANUARY 2004 - REVISED MAY 2004

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Output voltage range applied in high or low state, V _O (see Notes 1 and 2)0.5	V to V_{CC} + 0.5 V
Voltage range applied to any output in the power-off state, V _O (see Note 1)	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 3)	113°C/W
Storage temperature range, T _{stg}	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT		
Vcc	Supply voltage		2	5.5	V		
		V _{CC} = 2 V	1.5				
.,	High level input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V		
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} ×0.7		V		
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7				
		V _{CC} = 2 V		0.5			
.,		V _{CC} = 2.3 V to 2.7 V		V _{CC} ×0.3	.,		
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V		
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		V _{CC} ×0.3			
VI	Input voltage		0	5.5	V		
٧o	Output voltage		0	VCC	V		
		V _{CC} = 2 V		-50	μΑ		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2			
ЮН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		mA			
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12			
		V _{CC} = 2 V		50	μΑ		
	Laveland autout amount	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2			
IOL	Low-level output current	V _{CC} = 3 V to 3.6 V		6	mA		
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200			
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V		
		V _{CC} = 4.5 V to 5.5 V		20			
TA	Operating free-air temperature		-40	105	°C		

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	UNIT
	$I_{OH} = -50 \mu\text{A}$	2 V to 5.5 V	V _{CC} -0.1			
.,,	$I_{OH} = -2 \text{ mA}$	2.3 V	2			.,
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48			V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
V	I _{OL} = 2 mA	2.3 V			0.4	V
VOL	I _{OL} = 6 mA	3 V			0.44	V
	$I_{OL} = 12 \text{ mA}$	4.5 V			0.55	
lį	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
loff	V_I or $V_O = 0$ to 5.5 V	0 V			5	μΑ
Ci	$V_I = V_{CC}$ or GND	3.3 V		1.9		pF

SN74LV11A-EP TRIPLE 3-INPUT POSITIVE-AND GATE

SCLS564A - JANUARY 2004 - REVISED MAY 2004

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

ĺ	DADAMETED	FROM	то	LOAD	TA	λ = 25°C	;		MAY	
PARAMETER		(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
	t _{pd}	A, B, or C	Υ	$C_L = 50 pF$		9.9	17.5	1	21	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	Վ = 25° C	;	MINI	MAV	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
t _{pd}	A, B, or C	Υ	C _L = 50 pF		7.2	12.3	1	14	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	TO LOAD		T,	<u> </u> = 25°C	;	84181	MAV	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
^t pd	A, B, or C	Υ	C _L = 50 pF		5.4	7.9	1	9	ns

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

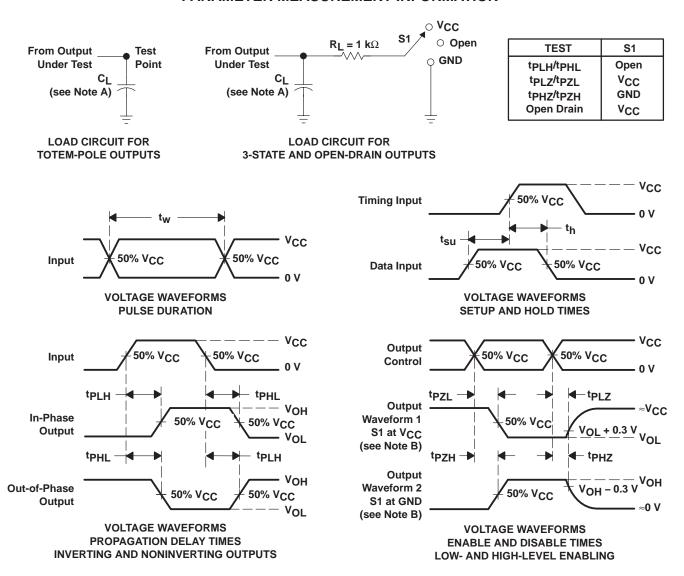
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
VOL(V)	Quiet output, minimum dynamic VOL		0	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.2		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

		PARAMETER	TEST CO	VCC	TYP	UNIT	
	C .	Dower discination conscitance	C:	f 40 MH-	3.3 V	13.9	۲
ı	Cpd	Power dissipation capacitance	$C_L = 50 pF$,	f = 10 MHz	5 V	15.4	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV11ATPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV11AEP	Samples
V62/04692-01XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV11AEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LV11A-EP:

• Automotive: SN74LV11A-Q1

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width							
В0	Dimension designed to accommodate the component length							
K0	O Dimension designed to accommodate the component thickness							
W	Overall width of the carrier tape							
P1	Pitch between successive cavity centers							

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV11ATPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

Device		Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74LV11ATPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0	



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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